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Appts. for fabricating semiconductor devices - including a gas discharge pipe connected to sealing door where devices are charged and discharged
Patent Assignee: NEC YAMAGATA LTD

Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 5251426	A	19930928	JP 9246524	A	19920304	199343	B

Priority Applications (Number Kind Date): JP 9246524 A (19920304)

Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 5251426	A		3	H01L-021/31	

Abstract:

JP 5251426 A

Appts. comprises a gas discharge pipe connected to the sealing door provided at the side where semiconductor devices are charged and discharged.

USE - Used for depositing oxide films, nitride films, etc. under low pressure.

Dwg.1/2

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